

ABSTRACT

Provided is a semiconductor wafer surface protection film that allows rear surface grinding without damage even for a stiff and fragile semiconductor wafer. Specifically, the semiconductor wafer surface protection film includes base layer (A) having storage elastic modulus $G_A(150)$ equal to or higher than 1 MPa at a temperature of 150°C and softening layer (B) having storage elastic modulus $G_B(120 \text{ to } 180)$ lower than 0.05 MPa at a temperature of 120 to 180°C and storage elastic modulus $G_B(40)$ equal to or higher than 10 MPa at a temperature of 40°C.